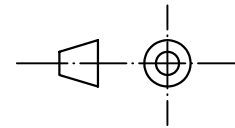


Recommended mounting:

Transmission lines on application PCB must be in level with T1
 For attachment use 2x M1.6 (or UNC 0-80) screws
 Bonding, use 25 - 75 um Au wires
 Note: For T1 use 250 um Au ribbon or 2x 25 um wires, keep short

All dimensions in mm



Tolerances +/-0.05 mm unless otherwise stated

Pin	Designation	Type
T1	RF output	Bond pad
T2	Tune 0V - +20V	Bond pad
T3	Bias +11V - +16V	Bond pad
GND	Ground 0V	Bond pad
Case	Ground 0V	

Design	Product	Scale	Design rev.
	VO3280_/__	2:1	
Drawn	Description	Release date	
CS	Interface Control Drawing	06 10 24	
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